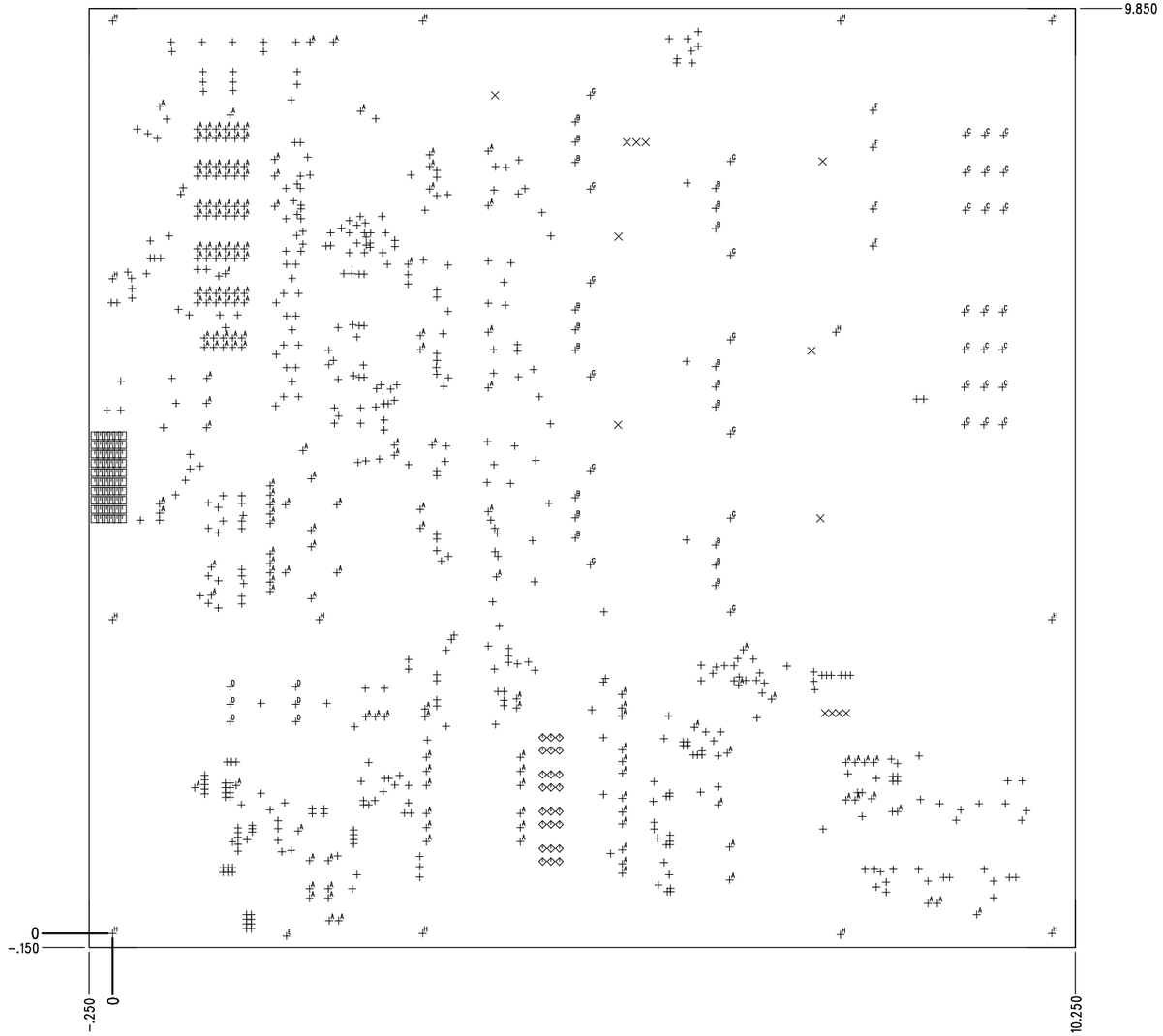
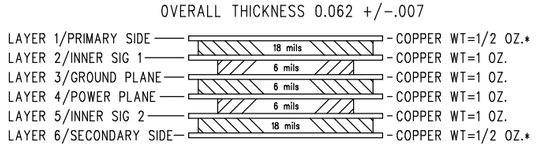
REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED



NOTES

1. LATEST VERSION OF ALL REFERENCED SPECIFICATIONS TO BE USED UNLESS OTHERWISE SPECIFIED.
2. FABRICATE IN ACCORDANCE WITH IPC-6012B, CLASS 2 UNLESS OTHERWISE SPECIFIED.
3. INSPECT IN ACCORDANCE WITH IPC-6012B, CLASS 2 UNLESS OTHERWISE SPECIFIED.
4. MATERIAL: HIGH TEMP FR4 (POLYCLAD FR370 OR EQUIVALENT). SEE LAYER STACKUP FOR THICKNESS. FINISHED BOARD MUST MEET UL94V-0.
5. PLATED-THRU HOLES TO HAVE A COPPER WALL THICKNESS NOT LESS THAN 0.001" THICKNESS TO BE DETERMINED BY IPC-6012B, CLASS 2.
6. SILKSCREEN NOMENCLATURE NOT TO COVER ANY PORTION OF A COMPONENT PAD. FABRICATOR TO CLIP ANY NON-CONFORMING SILKSCREEN NOMENCLATURE. DO NOT REMOVE SILKSCREEN FROM TENTED VIAS.
7. UL LOGO AND DATE CODE & VENDOR CODE MUST APPEAR IN ETCH ON PRIMARY SIDE. SECONDARY SIDE IS ACCEPTABLE IF THERE IS NO ROOM ON PRIMARY SIDE.
8. USE LPI SOLDER MASK OVER BARE COPPER PER IPC-SM-840C, CLASS 2.
9. SOLDER MASK SHALL BE CAPABLE OF FIVE SOLDER EXPOSURES AT 500 DEGREES F.
10. TOOLING HOLES MUST BE PRIMARY DRILLED AT THE SAME TIME AS PLATED-THRU HOLES. ALL HOLES MUST BE WITHIN 0.003" OF RADIAL TRUE POSITION.
11. DIMENSIONAL TOLERANCES ON PCB ARE AS FOLLOWS UNLESS OTHERWISE SPECIFIED.
    HOLE TO HOLE +/-.005"
    HOLE TO EDGE +/-.010"
    EDGE TO EDGE +/-.010"
12. PADS MUST BE FINISHED TO WITHIN +/-.0015" OF THE MINOR DIMENSION (PAD WIDTH) & +/-0.002" OF THE MAJOR DIMENSION (PAD LENGTH).
13. GLOBAL AND LOCAL FIDUCIALS MUST BE FREE OF ANY MARKINGS.
14. FULL NETLIST TESTING REQUIRED UNLESS OTHERWISE SPECIFIED. TESTING SHOULD CONFORM TO IPC-9252.
15. REMOVAL OF NON-FUNCTIONAL PADS ON INNER LAYERS ALLOWED.
16. THEIVING OF OUTER LAYERS IS ACCEPTABLE AS LONG AS THE COPPER IS KEPT A MININMUM OF 0.200" FROM ANY DESIGN FEATURE.
17. PRIOR TO BOARD FABRICATION, COMPARE GERBER DATA TO SUPPLIED IPC-D-356A NETLIST. REPORT ALL DISCREPANCIES.
18. ENTIRE BOARD TO BE IMMERSION GOLD PLATED. 2 TO 5 MICROINCHES OVER 100 MICROINCHES MINIMUM OF ELECTROLESS NICKEL.
19. BOARD TO BE ROHS/REACH COMPLIANT.

OVERALL THICKNESS 0.062 +/-.007



*PRIOR TO PLATING

LAYER STACKUP

SCALE: NONE

SIZE	QTY	SYM	PLATED	TOL
12	467	+	YES	+0.000/-0.012
20	13	×	YES	+/-0.003
24	60	□	YES	+/-0.002
25	24	◇	YES	+/-0.003
40	183	A	YES	+/-0.003
65	18	B	YES	+/-0.003
67	21	C	YES	+/-0.003
73	6	D	NO	+/-0.003
79	1	E	NO	+/-0.002
80	4	F	YES	+/-0.002
105	12	G	YES	+/-0.003
170	13	H	NO	+/-0.002

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN INCHES AND APPLY AFTER PROCESSING TOLERANCES.

TOLERANCES
.X ± .1 .XXX ± .005
.XX ± .01 ANGLES ± 2

DRAWN	iDESIGN	10/21/14
CHECKED		
APPROVED		
APPROVED		
REMOVE BURRS AND SHARP EDGES		

Boston Engineering Corporation
411 Waverly Oaks Rd. Suite 114
Waltham, MA 02452

TITLE
ISOLATED 3-PHASE INVERTER PLATFORM
FABRICATION DRAWING

SYM	SIZE	DRAWING NO.	REV
	C	3240G01	3

SCALE 1/1 SHEET 1 OF 1